ABSTRACT

WIRE BUMP MATERIAL

The present invention was held in order to resolve problems on above-mentioned conventional wire bumping material.

This invention has the following purposes :

(1) approximating Au-Ag alloy bumping balls to bond Al pads to ideal sphere shape

(2) increasing assurance of Au-Ag alloy bump bonding to Al pads

(3) shortening tail length of Au-Ag alloy bump

(4) improving anti-Au consumption into solder

(5) decreasing contamination of capillary tip by bump wire and hole around tip

Means for resolution

Au-Ag alloy for wire bumping comprising wherein Au, which purity is more than 99.99 mass %, comprising Au matrix and a particle of additive elements, consisting of 1 to 40 mass % Ag, which purity is more than 99.99 mass %.